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(54) COPPER FOIL COATED WITH HEAT-RESISTANT ADHESIVE LAYER, AND LEAD FRAME FITTED WITH HEAT DISSIPATION PLATE AND SEMICONDUCTOR DEVICE

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a resin-sealed semiconductor device capable of being produced by a simplified step of producing a heat spreader, excellent in electrical properties and free from reflow cracking.

SOLUTION: This invention provides a copper foil coated with a heat-resistant adhesive layer, prepared by forming a layer of an adhesive of a heat-resistant resin composition containing 10-80wt.%, based on the heat-resistant resin, silicone rubber filler having surface epoxy or amido groups, 0.5-10wt.% organic solvent, 0.5-20wt.% crosslinking agent and at least one heat-resistant resin selected among aromatic polyamides, aromatic polyimides, aromatic polyamide imides, aromatic polyether amides, aromatic polyether imides and aromatic polyether amide imides on either surface of a 50-200µm thick copper foil and a lead frame and a semiconductor using the foil.